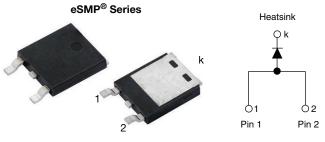
**Vishay Semiconductors** 





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SlimDPAK (TO-252AE)

## LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS						
I <sub>F(AV)</sub> 4 A						
V <sub>R</sub>	200 V					
V <sub>F</sub> at I <sub>F</sub>	0.71 V					
t <sub>rr</sub> (typ.)	16 ns					
T <sub>J</sub> max.	175 °C					
Package	SlimDPAK (TO-252AE)					
Circuit configuration	Single					

## **FEATURES**

- Hyperfast recovery time
- 175 °C max. operating junction temperature
- Low forward voltage drop reduced Q<sub>rr</sub> and soft recovery
- Low leakage current
- Very low profile typical height of 1.3 mm
- · Ideal for automated placement
- · Polyimide passivation for high reliability standard
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Meets JESD 201 class 2 whisker test
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

## **DESCRIPTION / APPLICATIONS**

State of the art hyper fast recovery rectifiers with optimized performance of forward voltage drop and hyper fast recovery time.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness, and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS inverters, or as freewheeling diodes. Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

## **MECHANICAL DATA**

Case: SlimDPAK (TO-252AE)

Molding compound meets UL 94 V-0 flammability rating Halogen-free, RoHS-compliant

Terminals: matte tin plated leads, solderable per J-STD-002

ABSOLUTE MAXIMUM RATINGS						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Peak repetitive reverse voltage	V <sub>RRM</sub>		200	V		
Average rectified forward current	I <sub>F(AV)</sub>	T <sub>C</sub> = 167 °C	4	•		
Non-repetitive peak surge current	I <sub>FSM</sub>	$T_J$ = 25 °C, 10 ms sine pulse wave	100	A		
Operating junction and storage temperatures	T <sub>J</sub> , T <sub>Stg</sub>		-55 to +175	°C		

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 $^{\circ}$ C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Breakdown voltage, blocking voltage	$V_{BR}, V_{R}$	I <sub>R</sub> = 100 μA	200	-	-		
Famuentushara	V <sub>F</sub>	$I_F = 4 A$	-	0.88	1.0	V	
Forward voltage		I <sub>F</sub> = 4 A, T <sub>J</sub> = 150 °C	-	0.71	0.80		
Reverse leakage current	I <sub>R</sub>	V <sub>R</sub> = V <sub>R</sub> rated	-	-	3		
neverse leakage current		$T_J = 150 \text{ °C}, V_R = V_R \text{ rated}$	-	-	80	μA	
Junction capacitance	CT	V <sub>R</sub> = 200 V	-	17	-	pF	

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<b>DYNAMIC RECOVERY CHARACTERISTICS</b> ( $T_J = 25 \text{ °C}$ unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS		
		$I_F = 1.0 \text{ A}, \text{ d}I_F/\text{d}t =$	100 A/µs, V <sub>R</sub> = 30 V	-	16	-		
Reverse recovery time	+	I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 1 A	$I_F = 0.5 \text{ A}, I_R = 1 \text{ A}, I_{RR} = 0.25 \text{ A}$			25		
neverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	20	-	- ns - A	
		T <sub>J</sub> = 125 °C	I <sub>F</sub> = 4 A dI <sub>F</sub> /dt = 200 A/µs V <sub>R</sub> = 160 V	-	30	-		
Peak recovery current		T <sub>J</sub> = 25 °C		-	2.5	-		
Peak recovery current	IRRM	T <sub>J</sub> = 125 °C		-	4	-		
	0	T <sub>J</sub> = 25 °C		-	25	-	nC	
Reverse recovery charge	Q <sub>rr</sub>	T <sub>J</sub> = 125 °C		-	60	-	nc	

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-55	-	175	°C	
Thermal resistance, junction to ambient	R <sub>thJA</sub> <sup>(1)(2)</sup>		-	73	90	°C/W	
Thermal resistance, junction to mount	R <sub>thJM</sub> <sup>(3)</sup>		-	2.1	2.5	°C/W	
Weight			-	0.20	-	g	
Marking device		Case style SlimDPAK (TO-252AE)		4EV	H02		

### Notes

<sup>(1)</sup> The heat generated must be less than thermal conductivity from junction to ambient;  $dP_D/dT_J < 1R_{thJA}$ 

<sup>(2)</sup> Free air, mounted or recommended copper pad area; thermal resistance R<sub>thJA</sub> - junction to ambient

<sup>(3)</sup> Mounted on infinite heatsink

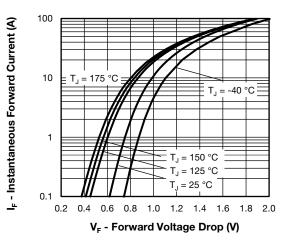


Fig. 1 - Typical Forward Voltage Drop Characteristics

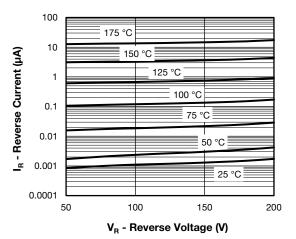


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage



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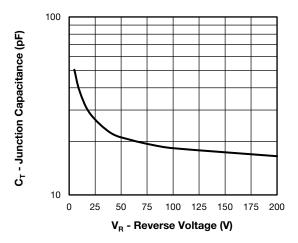


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

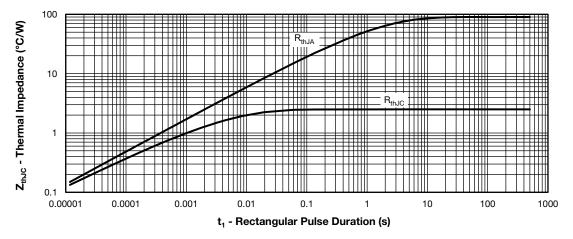
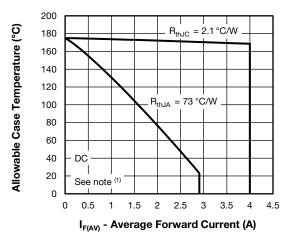
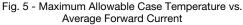


Fig. 4 - Maximum Thermal Impedance ZthJC Characteristics





### Note

<sup>(1)</sup> Formula used:  $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$ ;

 $\begin{array}{l} \mathsf{Pd} = \mathsf{forward} \ \mathsf{power} \ \mathsf{loss} = \mathsf{I}_{\mathsf{F}(\mathsf{AV})} \times \mathsf{V}_{\mathsf{FM}} \ \mathsf{at} \ (\mathsf{I}_{\mathsf{F}(\mathsf{AV})}/\mathsf{D}) \ (\mathsf{see} \ \mathsf{fig.} \ \mathsf{6}); \\ \mathsf{Pd}_{\mathsf{REV}} = \mathsf{inverse} \ \mathsf{power} \ \mathsf{loss} = \mathsf{V}_{\mathsf{R1}} \times \mathsf{I}_{\mathsf{R}} \ (\mathsf{1} - \mathsf{D}); \ \mathsf{I}_{\mathsf{R}} \ \mathsf{at} \ \mathsf{V}_{\mathsf{R1}} = \mathsf{rated} \ \mathsf{V}_{\mathsf{R}} \end{array}$ 

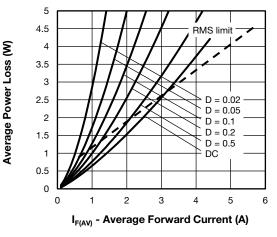


Fig. 6 - Forward Power Loss Characteristics

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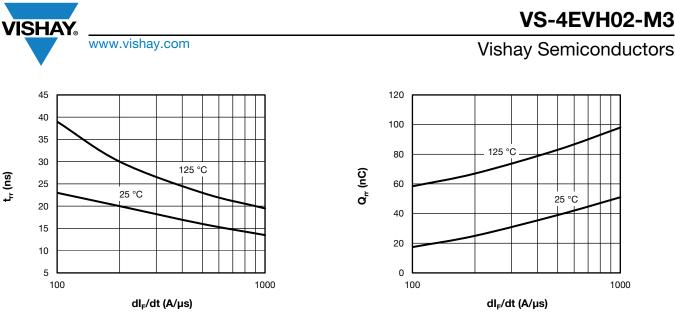


Fig. 7 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt



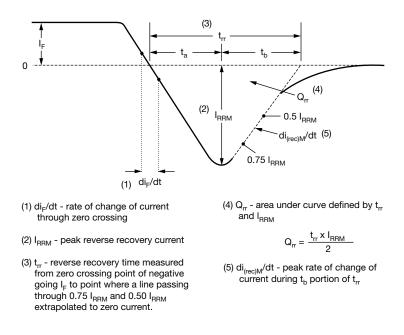


Fig. 9 - Reverse Recovery Waveform and Definitions



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## **ORDERING INFORMATION TABLE**

Device code	VS-	4	E	v	н	02	-M3
	1	2	3	4	5	6	7
			hay Sen rent rati		•	oduct	
		- Circ	cuit conf	iguration	,		
	4		single o SlimDP				
	5		cess typ • hyper f		very		
	6	- Vol	tage coo	le (02 =	200 V)		
	7	- Env	vironmer	ntal digit	:		
		-M3	3 = halog	gen-free	, RoHS	complia	ant, and

ORDERING INFORMATION (Example)								
PREFERRED P/N	REFERRED P/N QUANTITY PER REEL MINIMUM ORDER QUANTITY PACKAGING DESCRIPTION							
VS-4EVH02-M3/I	4500	4500	13"diameter plastic tape and reel					

LINKS TO RELATED DOCUMENTS					
Dimensions	www.vishay.com/doc?96081				
Part marking information	www.vishay.com/doc?96085				
Packaging information	www.vishay.com/doc?88869				
SPICE model	www.vishay.com/doc?97123				





SlimDPAK

## **DIMENSIONS** in inches (millimeters)





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